



TG-CJ-Li-43-43-6-PF

Ceramic Heatsink

Version 1.220917

Ceramic Heatsink

T-Global's range of ceramic heatsinks have been designed from a proprietary blend of engineering ceramics to offer superior thermal management for the most demanding of applications. Compared to aluminium, ceramics confer additional benefits such as electrically isolating, resistant to corrosion, low weight and does not act like an antenna. The addition of a pre-applied thermal tape further reduces the manufacturing complexity when compared to aluminum heatsinks.

Features

Large contact area Low weight High breakdown voltage Excellent heat spreader Custom shapes possible

Applications

LÉD, M/B, P/S, LCD, TV, Notebook, PC, PC Telecom Device, Wireless Hub, Power transistor, Power module, CPU, Chip IC

Properties

REACH Compliant

ROHS Compliant

	Technical Ceramic		
Property	Property Property		
	Density	g/cm³	3.66
	Water Absorption	%	0.002
Physical Property	Sinter Temperature	°C	1700
	Acid Resistance	mg/cm³	≦0.2
	Alkali	mg/cm³	≦0.2
	Mohs Hardness	ΗV	9
Mechanical Property	Bend Strength	Мра	≧ 610
roperty	Compression Intensity	Мра	≧ 620
	Maximum Working Temperature	°C	1400
Thormal Droporty	Thermal Expansion Coefficient	(1x10⁵) mm/°C	7.8~8.3
Thermal Property	Thermal Shock Resistance	T (°C)	200
	Thermal Conductivity	W/m.k.	40~51
	Resisting Rate of Volume	O°C	1016
Electrical Prop- erty	DC Breakdown Strength	KV/mm	15.2~16.7
	Insulation Breakdown Intensity	KV/mm	18
	Dielectric Constant (1MHz)	(E)	10
	Dielectric Dissipation	(tg o)	0.4*10 ⁻³

Part Number Information

TG-CJ-Li-43-43-6-PF

Product	Length	Width	Depth	Adhesive
TG-CJ-Li-43-43-6-PF	43	43	6	1 Sided Tape
* All measurements in mm				

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Tel: +44 (0)1455 553 510 Email: sales@tglobaltechnology.com Web: www.tglobaltechnology.com Skype: tglobal.technology VAT #: GB 116 662 714 **NOTICE:** The information contained herein is to the best of our knowledge true and accurate. However, since the varied conditions of potential use are beyond our control, all recommendations or suggestions are presented without guarantee or responsibility on our part and users should make their own test to determine the suitability of our products in any specific situation. This product is sold without warranty either expressed or implied, of fitness for a particular purpose or otherwise, except that this product shall be of standard quality, and except to the extent otherwise stated T-Global Technology Europe and North America's invoice, quotation, or order acknowledgment. We disclaim any and liability incurred in connection with the use of information contained herein, or otherwise. All risks of such are assumed by the user. Furthermore, nothing contained herein shall be construed as a recommendation to use any process or to manufacture or to use any product in conflict with existing future patents covering any product or material or its use.



Li98 Thermal Tape

Version 1.200917

Thermal Tape

Li98 thermal tapes are double-sided thermal interface tapes and provide exceptional bonding properties between electronic components and heat sinks, eliminating the need for mechanical fasteners. Li98 can be offered in various formats such as sheets, rolls and die cut parts depending on the applications and have proven reliability under various mechanical, thermal, and environmental stresses.

Features

Good adhesion (Acrylic PSA) Great reliability Cost effective with great performance Easy to assemble

Applications

Electronic components: IC, CPU, MOS LED, M/B, P/S, Heat Sink LCD, TV, Notebook PC, PC Telecom Device, Wireless Hub, etc. DDR II Module, DVD Applications, Hand-set applications, etc.

Properties

REACH Compliant

ROHS Compliant

Property	Li98		Unit	Tolerance	Test Method	
Colour	Green	Red	-	-	Visual	
Thickness	0.15	0.25	mm	-	ASTM D374	
THICKNESS	0.0059	0.00984	inch	-	ASTM D374	
Thermal Conductivity	0.95	0.95	W/mK	±0.10%	ASTM D5470	
Continuous Working Temperature	-30 t	o 120	°C	-	-	
Short Time Using Temperature	20	00	°C	-	-	
Density	1.85		g/cm³	±1.3	ASTM D792	
Tensile Strength	200	400	psi	-	ASTM D412	
Glass Transition Temperature	-30		°C	-	-	
Initial Tack	10	8	cm	-	PSTC-6	
Lap Shear Strength	61	55	N/cm ²	-	ASTM D1002	
Die Shear Strength 25 °C	120	109	N/cm ²	±0.2	-	
Die Shear Strength 80 °C	69	68	N/cm ²		-	
Holding Power 1000g 25 °C	>10	000	min		PSTC-7	
Holding Power 1000g 80 °C	>10000		min		PSTC-7	
90° Peeling Strength	>10	>12	N/in		ASTM D3330	
Dielectric Breakdown Voltage (AC)	2	3	kV/mm	±0.10%	ASTM D149	
Dielectric Breakdown Voltage (DC)	3	4	kV/mm	±0.10%	ASTM D149	
Reinforcement Carrier	Fiberglass Mesh		-	-	-	

Thermal Impedance vs Pressure vs Deflection



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Part Number Information

Li98

Product	Length	Width	Thickness	Adhesive
Li98	50mm	20	0.15	-

* All measurements in mm

Standard Weights & Dimensional Tolerance

	Thickness (mm)	0.15 Weight (gr)	0.25 Weight (gr)
	100x100	2.78	4.63
Size	150x150	6.24	10.41
	300x300	24.98	41.63
	320x320	28.42	47.36

* All measurements in weights are in gr

** All sizes are in mm

Data

Digi-Key Part	T-Global Part
1168-1715-ND	LP0001/01-Li98-0.15
1168-1908-ND	LP0007/01-Li98-0.25
1168-1867-ND	LP0003/01-Li98-0.25
1168-1845-ND	TG-CPCB1-Li98-0.15
1168-1843-ND	TG-CPCB2-Li98-0.15
1168-1841-ND	TG-CPCB3-Li98-0.15
1168-1847-ND	LP0001/01-Li98-0.25
1168-1857-ND	LP0002/01-Li98-0.25
1168-1907-ND	LP0007/01-Li98-0.15
1168-1763-ND	LP0003/01-Li98-0.15
1168-1718-ND	LP0002/01-Li98-0.15
1168-1766-ND	LP0004/01-Li98-0.15
1168-1769-ND	LP0005/01-Li98-0.15
1168-1877-ND	LP0004/01-Li98-0.25
1168-1772-ND	LP0006/01-Li98-0.15
1168-1887-ND	LP0005/01-Li98-0.25
1168-1897-ND	LP0006/01-Li98-0.25

	Thickness (mm)	Tolerance (mm)	
	0.3	±0.03	
	0.5	±0.05	
	0.8	±0.08	
	1.0	±0.1	
	1.2	±0.12	
Die-Cut	1.5	±0.15	
Thickness	2.0	±0.2	
Tolerances	2.5 - 3.5	±0.25	
	4.0 - 4.5	±0.3	
	5.0	±0.35	
	6.0 - 8.0	±0.4	
	9.0	±0.45	
	10.0	±0.5	
	>10.0	±0.5	

Digi-Key Part	T-Global Part	Thickness	Material	Adhesive	Backing Carrier	Thermal Conductivity	
1168-1715-ND	LP0001/01-Li98-0.15	0.0007" (0.178mm)					
1168-1908-ND	LP0007/01-Li98-0.25						
1168-1867-ND	LP0003/01-Li98-0.25		Acrylic	Both	Fibergloop	2.0.14/m 1/	
1168-1845-ND	TG-CPCB1-Li98-0.15		Elastomer	sides	Fiberglass	2.0 W/m-K	
1168-1843-ND	TG-CPCB2-Li98-0.15						
1168-1841-ND	TG-CPCB3-Li98-0.15						

* Data for design engineer guidance only. Observed performance varies in application. Engineers are reminded to test the material in application.

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